



LCCC - 2.03 mm max height

LEADLESS CERAMIC CHIP CARRIER



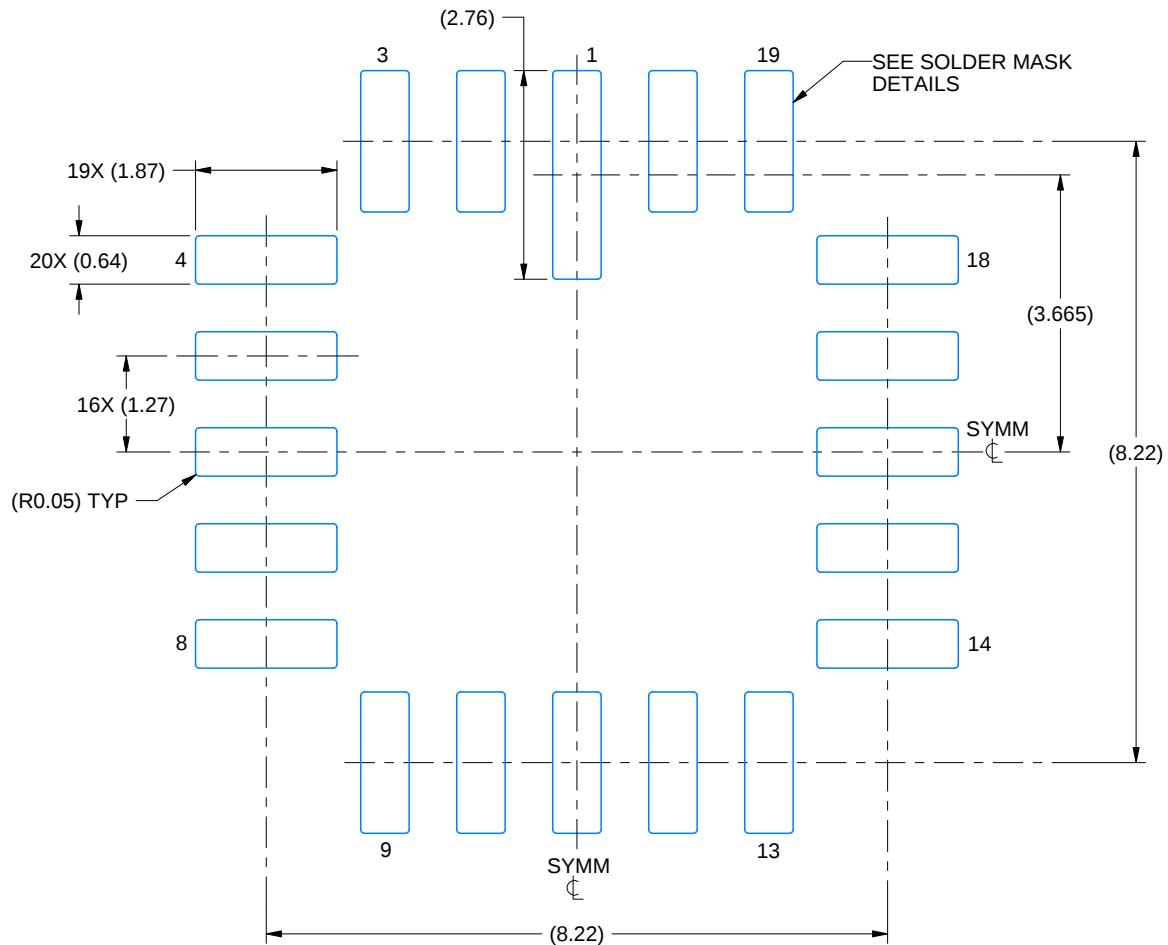
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package can be hermetically sealed with a metal lid.
4. Reference JEDEC Registration MS-004.
5. The terminals are gold-plated.

EXAMPLE BOARD LAYOUT

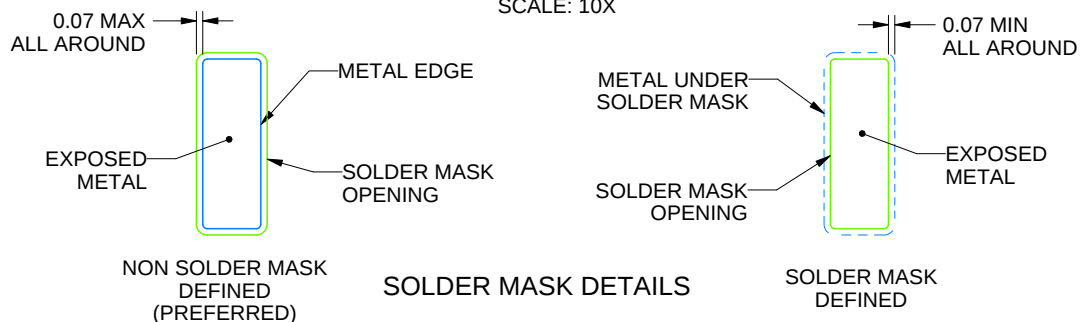
FK0020B

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LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



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NOTES: (continued)

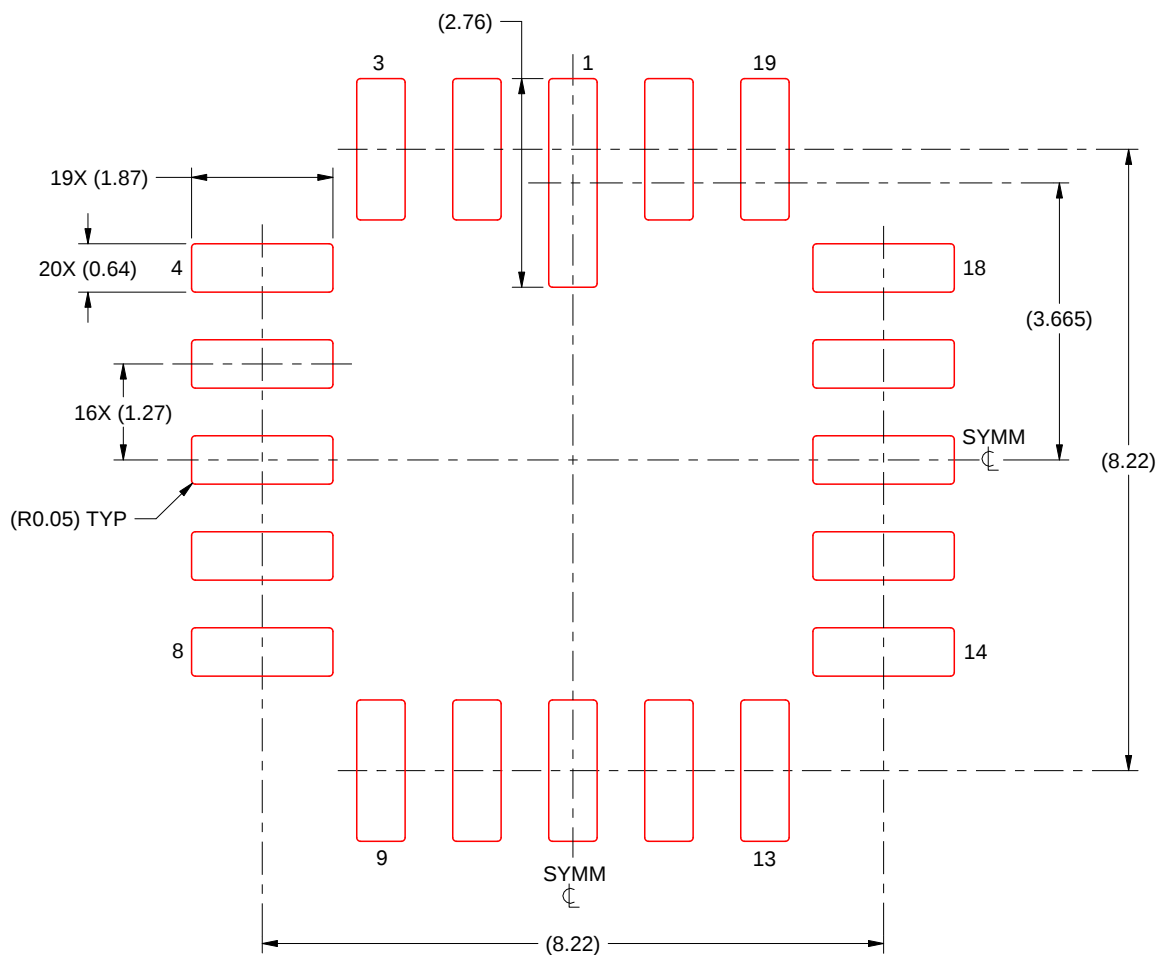
6. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slue271).

EXAMPLE STENCIL DESIGN

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SOLDER PASTE EXAMPLE
BASED ON 0.125 mm TICK STENCIL
SCALE: 10X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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